

Patent Abstracts of Japan

PUBLICATION NUMBER : 11289072
PUBLICATION DATE : 19-10-99

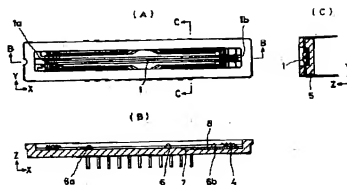
APPLICATION DATE : 01-04-98
APPLICATION NUMBER : 10088363

APPLICANT : SONY CORP;

INVENTOR : UCHIGAWA KUNIHARU;

INT.CL. : H01L 27/14 H04N 1/028

TITLE : LINEAR SENSOR AND PACKAGE THEREFOR



ABSTRACT : PROBLEM TO BE SOLVED: To prevent the generation of the bending or breaking of a solid image pickup element chip or the peeling of adhesive on a boundary face with a package for housing the solid image pickup element chip or the solid image pickup element chip, by removing or reducing any thermal stress due to a linear expansion coefficient difference between the slim solid image pickup element chip and the package.

SOLUTION: This linear sensor is formed so that the die attach part of a package 5 for a linear sensor can be constituted of a fixed part 6a and a movable part 8 formed so as to be slidable to the longitudinal direction of the package for the linear sensor, and that a solid image pickup element chip 1 can be adhered to the fixed part 6a of the die attach part and the movable part 8.

COPYRIGHT: (C)1999,JPO